LHCb ГНСр

LHCb Silicon Tracker electronics: from R&D to preproduction





Silicon Tracker geometry

- Trigger Tracker:
 1 station @ 4 layers
 between RICH1 and magnet
- Inner Tracker:
 3 stations @ 4 layers each around beampipe at stations T1-T3 (between magnet and RICH2)
- Different geometry but same electronics!





Station overview

TT station



IT station



143k channels



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• Frontend hybrids located outside acceptance



Flexcable prototype



- 3 500 um sensors in series with 39 cm flexcable (Ctot = 38 pF)
- Included in CERN X7 testbeam in Summer 2004 with Beetle 1.3 hybrid
- Measured S/N 16.5, in agreement with capacitance calculations



IT sensor layout

IT:

- 384 detector channels per ladder for IT, pitch 198 um, sensor thickness 410 um (2-sensor module) and 320 um (1-sensor module)
- Frontend hybrids inside detector acceptance



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Beetle frontend hybrids



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- 4-layer polyimide hybrid
 Beetle chip is only active device:
 0.25 um CMOS, rad-hard design
 128 channel charge integrator
 (see talk U. Trunk , session A3)
- 3 chip hybrid for IT (3x 128 ch)
- 4 chip hybrid for TT (4x 128 ch)



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Digital optical readout link





Jumper- + SCSI cable

 Polyimide + SCSI cable (LSZH) used for first 5 m of transmission for lower radiation doses to the service box electronics

 Preliminary cable tests over show good performance of line receiver: eye pattern of 'quasidigital' Beetle header



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Digitizer Board

- Key element of Service box, size 328 x 140 mm2
- Only connection of any hybrid to the outside world
- Receives data from one sensor ladder (3 or 4 Beetle chips)



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Digitizer Board systems

- Key components:
 - Differential line receiver
 - 8 bit 40 MSPS ADC
 - CERN GOL serializer
 - 2.5 Gbps VCSEL diode
- Additional components:
 - 1 QPLL chip for low-jitter clock generation close to GOLs
 - 1 DCU25F chip for environmental monitoring (voltages, temperatures) clock distribution
- Power, TTC signals, I2C slow control for hybrids are just passed through



Production of preseries

- PCB company and assembly company chosen, will remain fixed for later prodcution of full quantities
- 17 digitizer boards have been produced (will be used in module test setup)
- All BGA solder balls have been checked with X-ray to ensure reliable solder joints:
 no faulty solder joint among total of over 10000 balls
 → consider pad design compatible with BGA soldering
- electronic design will stay 99% identical (except for minor bugfixes)



Service box backplane

- Distribution of power, fast signals, slow control to digitizer boards
- Conservative design:
 4 layers, 6 mil technology
- Only active components are L4913 LHC pos. voltage regulators and LVDS clock IC's (tested to 70 krad)
- Easy cooling via flat watercooled heatsink
- First prototypes (8 slots) being assembled, tests next week
- Full backplane with 20 slots





Control Card

- Under development by • Universidade de Santiago de Compostela
- Provides TTC signals and slow control interface of each Service box
- Same size as Digitizer Board to fit • into crate
- Main components:
 - 1 TTCrq mezzanine
 - 2 SPECS slaves for slow control (I2C, temperature/humidity readout)







SPECS slave (Orsay) A. Vollhardt, Universität Zürich/Switzerland



Radiation qualification

- Expected radiation levels at service box location:
 <15 krad, <2E12 n/cm2 (1 MeV n eq.) for 10 year LHC running
- AD8129 line receiver tested up to 300 krad, 2E14 n/cm2
- TSA0801 ADC tested up to 60 krad (analogue and SEE test)
- ULM-Photonics VCSEL tested up to 300 krad, 3.6E12 n/cm2
- Fibre tested up to 2.2 Mrad
- (CERN GOL, QPLL, DCU25F tested to several Mrad)
- No failures of components
- Only slightly decreased performance measured for line receiver and optical fibre, well within system design margins
- All components qualified for use in service box



Optical power budget

Min. laser power into fibre:	-5.0	dBm
Max. Fibre attenuation 100 m:	0.5	dB
3 optical cable interfaces max. 0.5 dB per interface:	1.5	dB
Worst case average power at receiver:	-7.0	dbm
Worst case optical sensitivity SNAP12 receiver:	-16.0	dBm
Power margin:	9.0	dB

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O-RX card (Uni Heidelberg)

- Common LHCb effort lead by Physikalisches Institut, University Heidelberg
- Optical input directly compatible to used MTP fibre (SNAP12 compatible multi-channel receiver, 2.5 Gbps)
- 12x TLK2501 deserializer
- LHCClk x2 crystal oscillator on board
- Preseries of 28 ordered, expected for October





BER testing, eye pattern

- Dirk Wiedner (Heidelberg) made BER testing with pseudorandom data
- 3 days continous running (4E14 bits) without a single error

 Check eye pattern of optical signal with 5 GHz opto-electric converter: clean open eye



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TELL1 board (EPF Lausanne)



Common LHCb Effort, lead by EPF Lausanne, preseries expected until end of the year

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Conclusion + Outlook

- Silicon sensors chosen and production lot ordered, first batches arrive Jan 2005
- R&D for LHCb Silicon Tracker electronics complete
- First round of preseries in production
- Testing of full readout chain (detector + readout link + LHC timing hardware) in mechanical mock-up of TT station with pre-production hardware planned until end of the year
- Series production for electronic modules will start in Q2/2005



ADC TID testing

- TID Testing performed by injecting 5 MHz sinewave close to full scale and doing FFT analysis of digitized signal
- Plot SFDR and SNR for duration of irradiation, idea: any unlinearity will show up in SFDR, any gain loss in SNR



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ADC SEE testing

- One ADC was connected to high limit (all '1' at output), and one ADC to low limit (all '0')
- Both bytes were tested with logic gates in real time
- For each bit flip: output pulsed, connect output to counter
- All ADCs irradiated to 4.6E11 p/cm2
- For the complete campaign (4 ADC10040, 4 TSA0801), one 1 SEU was found ('1' to '0')